

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**SEMICONDUCTOR CHIP ASSEMBLIES, METHODS OF MAKING SAME AND COMPONENTS FOR SAME**  
the specification of which

☐ is attached hereto

☒ was filed on October 7, 1994 as United States Application Number 08/319,966.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before the application on which priority is claimed:

| PRIOR FOREIGN APPLICATION(S)   |                    |                                      |  |
|--|--------------------|--------------------------------------|--|
| COUNTRY  | APPLICATION NUMBER | DATE OF FILING<br>(day, month, year) | PRIORITY CLAIMED   |
| NONE   |                    |                                      | YES <input type="checkbox"/> NO <input type="checkbox"/> |
| LISTING OF FOREIGN APPLICATIONS CONTINUED ON PAGE 2 HEREOF <input type="checkbox"/> YES <input checked="" type="checkbox"/> NO |                    |                                      |  |

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

NONE

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

|                                       |                                 |   |
|---------------------------------------|---------------------------------|---|
| Application Serial Number: 08/030,194 | Filing Date: April 28, 1993     | Status (patented, pending, abandoned): Pending  |
| Application Serial Number: 07/765,928 | Filing Date: September 24, 1991 | Status (patented, pending, abandoned): Patented |
| Application Serial Number: 07/673,020 | Filing Date: March 21, 1991     | Status (patented, pending, abandoned): Patented |
| Application Serial Number: 07/586,758 | Filing Date: September 24, 1990 | Status (patented, pending, abandoned): Patented |

LISTING OF US APPLICATIONS CONTINUED ON PAGE 2 HEREOF: NO

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

Lawrence I. Lerner, Reg. No. 18,516; Sidney David, Reg. No. 22,768; Joseph E. Littenberg, Reg. No. 30,832; Arnold H. Krumholz, Reg. No. 25,428; William L. Mentlik, Reg. No. 27,108; John R. Nelson, Reg. No. 28,573; Roy H. Weoner, Reg. No. 28,350; Stephen B. Goldman, Reg. No. 28,512; Paul H. Kucharski, Reg. No. 28,800; Marcus J. Millet, Reg. No. 28,241; Bruce H. Sales, Reg. No. 32,783; Daniel H. Bohns, Reg. No. 18,694; Peter J. Butch III, Reg. No. 32,203; Keith E. Garman, Reg. No. 32,137; Robert B. Cohen, Reg. No. 32,768; Arnold B. Dompier, Reg. No. 28,738; Michael H. Teschner, Reg. No. 32,882; Jeffrey S. Dickey, Reg. No. 35,858; Gregory S. Gewirtz, Reg. No. 36,522; Jonathan A. David, Reg. No. 36,484; Shawn P. Foley, Reg. No. 33,071; Lawrence G. Fridman, Reg. No. 31,815; Christopher M. Pickett, Reg. No. 37,531.

|   |   |
|---|---|
| SEND CORRESPONDENCE TO:<br>LERNER, DAVID, LITTENBERG,<br>KRUMHOLZ & MENTLIK<br>600 South Avenue West<br>Westfield, New Jersey 07090 | DIRECT TELEPHONE CALLS TO:<br>(name and telephone number)<br><br>MARCUS J. MILLET<br>(908) 654-5000 |
|---|---|

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor (given name, family name): IGOR Y. KHANDROS

Inventor's signature \_\_\_\_\_ Date \_\_\_\_\_

Residence: ORINDA, CALIFORNIA      Citizenship: U.S.A.  
Post Office Address: 25 HACIENDAS ROAD, ORINDA, CALIFORNIA, 94563

Full name of second joint inventor, if any (given name, family name) THOMAS H. DISTEFANO

Second Inventor's signature Thomas H. Distefano Date OCTOBER 9, 1996

Residence: MONTE SERENO, CALIFORNIA      Citizenship: U.S.A.  
Post Office Address: 15363 ROBIN ANN LANE, MONTE SERENO, CA 95030

☐ NO Additional inventors are being named on separately numbered sheets attached hereto.

As a below-named inventor, I hereby declare that:

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☒ was filed on **October 7, 1994** as United States Application Number **08/319,966**.

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| COUNTRY                      | APPLICATION NUMBER | DATE OF FILING<br>(day, month, year) | PRIORITY CLAIMED   |
| NONE                         |                    |                                      | YES <input type="checkbox"/> NO <input type="checkbox"/> |

LISTING OF FOREIGN APPLICATIONS CONTINUED ON PAGE 2 HEREOF ☐ YES ☒ NO

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SEND CORRESPONDENCE TO:  
LERNER, DAVID, LITTENBERG,  
KRUMHOLZ & MENTLIK  
600 South Avenue West  
Westfield, New Jersey 07090

DIRECT TELEPHONE CALLS TO:  
(name and telephone number)

MARCUS J. MILLET  
(908) 654-5000

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Full name of sole or first inventor (given name, family name): **IGOR Y. KHANDROS**

Inventor's signature [Signature] Date 11/15/96

Residence: **ORINDA, CALIFORNIA** Citizenship: **U.S.A.**  
Post Office Address: **25 HACIENDAS ROAD, ORINDA, CALIFORNIA, 94563**

Full name of second joint inventor, if any (given name, family name) **THOMAS H. DISTEFANO**

Second Inventor's signature \_\_\_\_\_ Date \_\_\_\_\_

Residence: **MONTE SERENO, CALIFORNIA** Citizenship: **U.S.A.**  
Post Office Address: **15363 ROBIN ANN LANE, MONTE SERENO, CA 95030**

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the specification of which

☐ is attached hereto☐ was filed on \_\_\_\_\_ as Application Serial No. \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable)☒ was described and claimed in International Application No. PCT/US91/06920 filed 9/24/91 and as amended on \_\_\_\_\_ (if any)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

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|------------------------------|--------------------|--------------------------------------|---|
| COUNTRY                      | APPLICATION NUMBER | DATE OF FILING<br>(day, month, year) | PRIORITY<br>CLAIMED UNDER<br>35 U.S.C. 119                          |
| US                           | 07/586,758         | 9/24/90                              | YES <input checked="" type="checkbox"/> NO <input type="checkbox"/> |
| US                           | 07/673,020         | 3/21/91                              | YES <input checked="" type="checkbox"/> NO <input type="checkbox"/> |
|                              |                    |                                      | YES <input type="checkbox"/> NO <input type="checkbox"/>            |

LISTING OF FOREIGN APPLICATIONS CONTINUED ON PAGE 2 HEREOF. ☐ YES ☒ NO

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|                          |               |  |
|--------------------------|---------------|--|
| (Application Serial No.) | (Filing Date) | (Status)<br>(patented, pending, abandoned) |
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## SEND CORRESPONDENCE TO:

LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK  
600 South Avenue West  
Westfield, New Jersey 07090

## DIRECT TELEPHONE CALLS TO:

(name and telephone number)  
Joseph S. Littenberg  
(908) 654-5000

|     |                         |                       |                          |                        |
|-----|-------------------------|-----------------------|--------------------------|------------------------|
| 201 | FULL NAME OF INVENTOR   | LAST NAME             | FIRST NAME               | MIDDLE NAME            |
|     |                         | KHANDROS              | Igor                     | Y.                     |
|     | RESIDENCE & CITIZENSHIP | CITY                  | STATE OR FOREIGN COUNTRY | COUNTRY OF CITIZENSHIP |
|     |                         | Peekskill             | New York                 |                        |
|     | POST OFFICE ADDRESS     | CITY                  | STATE OR COUNTRY         | ZIP CODE               |
|     |                         | 503 Furnace Dock Road | Peekskill                | New York 10566         |
| 202 | FULL NAME OF INVENTOR   | LAST NAME             | FIRST NAME               | MIDDLE NAME            |
|     |                         | DISTEFANO             | Thomas                   | H.                     |
|     | RESIDENCE & CITIZENSHIP | CITY                  | STATE OR FOREIGN COUNTRY | COUNTRY OF CITIZENSHIP |
|     |                         | Bronxville            | New York                 | U.S.A.                 |
|     | POST OFFICE ADDRESS     | CITY                  | STATE OR COUNTRY         | ZIP CODE               |
|     |                         | 29 Birch Brook Road   | Bronxville               | New York 10708         |
| 203 | FULL NAME OF INVENTOR   | LAST NAME             | FIRST NAME               | MIDDLE NAME            |
|     |                         |                       |                          |                        |
|     | RESIDENCE & CITIZENSHIP | CITY                  | STATE OR FOREIGN COUNTRY | COUNTRY OF CITIZENSHIP |
|     |                         |                       |                          |                        |
|     | POST OFFICE ADDRESS     | CITY                  | STATE OR COUNTRY         | ZIP CODE               |
|     |                         |                       |                          |                        |

LISTING OF INVENTORS CONTINUED ON PAGE 2 HEREOF. ☐ YES ☒ NO

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

|                           |                           |                           |
|---------------------------|---------------------------|---------------------------|
| SIGNATURE OF INVENTOR 201 | SIGNATURE OF INVENTOR 202 | SIGNATURE OF INVENTOR 203 |
| <i>[Signature]</i>        | <i>[Signature]</i>        |                           |
| DATE                      | DATE                      | DATE                      |
| 3/3/93                    | 3/16/93                   |                           |

SEE PAGE 2 ATTACHED, SIGNED AND MADE A PART HEREOF. ☐ YES ☒ NO

\*Where use of Page 2 of this Declaration is necessary, only Page 2 is signed.